

SERIAL E<sup>2</sup>PROM  
**TC89101P, TC89102P**

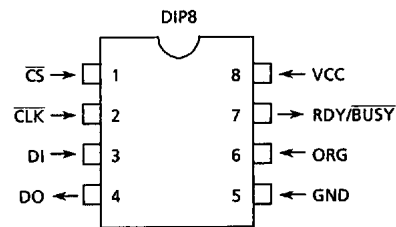
The TC89101P is a 1024-bit serial E<sup>2</sup>PROM. The TC89102P is a 2048-bit serial E<sup>2</sup>PROM. These are fabricated with floating gate CMOS technology.

PART No.	CAPACITY	ORGANIZATION	PACKAGE
TC89101P	1024-bit	128 x 8-bit or 64 x 16-bit	DIP8
TC89102P	2048-bit	256 x 8-bit or 128 x 16-bit	

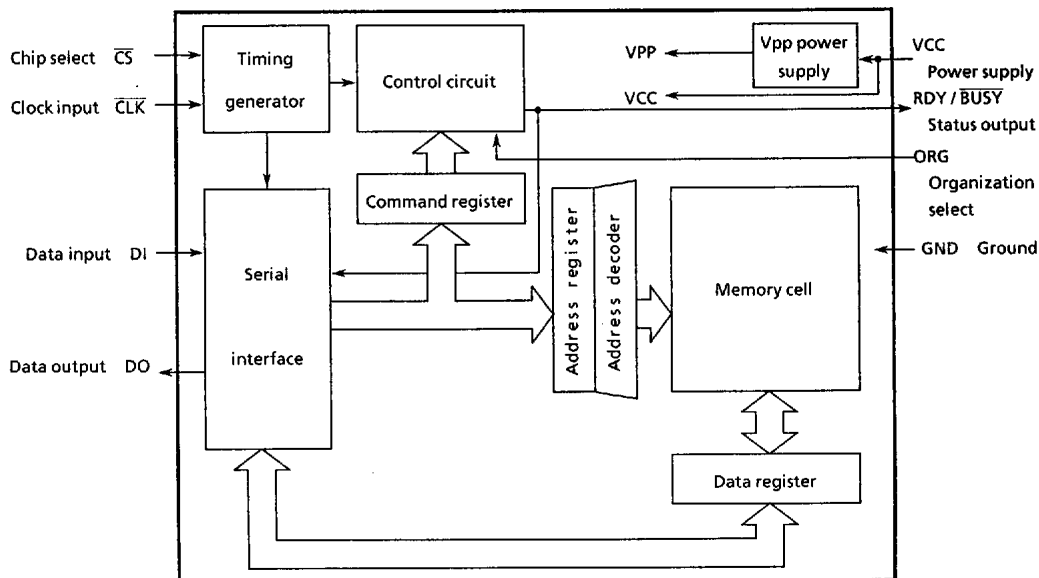
**FEATURES**

- ◆ Single 5V Supply
- ◆ Low Power Dissipations
- ◆ Serial Interface
- ◆ Self timed Program cycle (Built-in Timer)
- ◆ Ready/Busy status signal
- ◆ Erase/Write Enable and Disable by software
- ◆ Erase/Write Disable for low power supply
- ◆ Program and Chip Erase
- ◆ User Selectable Organization 8-bit or 16-bit

**PIN ASSIGNMENT (TOP VIEW)**



**BLOCK DIAGRAM**



PIN FUNCTION

PIN NAME	Input/Output	FUNCTIONS
$\overline{CS}$	Input	Chip select Chip is enabled when $\overline{CS}$ is at "L" level. Set $\overline{CS}$ to "H" level before executing instructions.
$\overline{CLK}$	Input	Clock input The DI data is latched at the rising edge of $\overline{CLK}$ . The data is output from DO at the falling edge of $\overline{CLK}$ . $\overline{CLK}$ is enabled when $\overline{CS}$ is at "L" level.
DI	Input	Serial data input The address, command and data input pin.
DO	Output	Serial data output The data output pin.
ORG	Input	Organization select The 16-bit organization is selected when ORG is "H" level. The 8-bit organization is selected when ORG is "L" level.
RDY/ $\overline{BUSY}$	Output	Status output "L" level is output during program or chip erase operation. "H" level is output when program or chip erase operation is completed.
VCC	Power supply	+ 5V
GND		0V (GND)

OPERATIONAL DESCRIPTION

1. INSTRUCTION SET

(1) TC89101

Instruction	Address		Command	Data	
	128 x 8-bit	64 x 16-bit	C0 C1 C2 C3	128 x 8-bit	64 x 16-bit
Read	A0 ~ A6, 0	A0 ~ A5, 00	1 0 0 0 0 0 0 0 0		
Program	A0 ~ A6, 0	A0 ~ A5, 00	0 1 1 0 0 0 0 0 0	D0 ~ D7	D0 ~ D15
Chip Erase	*****	*****	0 0 1 1 0 0 0 0 0		
Busy Monitor	*****	*****	1 0 1 1 0 0 0 0 0		
E/W Enable	*****	*****	1 0 0 1 0 0 0 0 0		
E/W Disable	*****	*****	1 1 0 1 0 0 0 0 0		

\*: don't care

## (2) TC89102

Instruction	Address		Command	Data	
	256 × 8-bit	128 × 16-bit	C0C1 C2 C3	256 × 8-bit	128 × 16-bit
Read	A0 ~ A7	A0 ~ A6, 0	1 0 0 0 0 0 0 0		
Program	A0 ~ A7	A0 ~ A6, 0	0 1 1 0 0 0 0 0	D0 ~ D7	D0 ~ D15
Chip Erase	*****	*****	0 0 1 1 0 0 0 0		
Busy Monitor	*****	*****	1 0 1 1 0 0 0 0		
E/W Enable	*****	*****	1 0 0 1 0 0 0 0		
E/W Disable	*****	*****	1 1 0 1 0 0 0 0		

\*: don't care

## 2. OPERATION METHOD

Set  $\overline{CS}$  and  $\overline{CLK}$  to "H" level before executing instruction.  $\overline{CS}$  changes to "L" level, then  $\overline{CLK}$  is enabled and operates as the sync signal for serial I/O. The DI data is latched at the rising edge of  $\overline{CLK}$ . The data is output from DO at the falling edge of  $\overline{CLK}$ .

Execute instruction only when RDY/ $\overline{BUSY}$  status signal is "H" level. However Busy Monitor instruction can be executed whenever.

Uses only commands which are included in the Instruction Set listed above.

## (1) Read

Executing Read instruction reads out the memory data at the specified address and outputs it serially from DO.

## (2) Program

Executing Program instruction automatically starts internal rewriting of the memory data at the specified address with the input data.

After Program instruction is input,  $\overline{CS}$  can be set to "H" level ever while the internal rewriting process is operating.

## (3) Chip Erase

Executing Chip Erase instruction automatically Starts internal erasing of the memory data at all address.

After Chip Erase instruction is input,  $\overline{CS}$  can be set to "H" level even while the internal erasing process is operating.

## (4) Busy Monitor

Executing Busy Monitor instruction outputs the RDY/ $\overline{BUSY}$  status signal from DO.

"L" level is output during Program or Chip Erase operation. "H" level is output when Program or Chip Erase operation is completed.

The RDY/ $\overline{BUSY}$  status signal is output until  $\overline{CS}$  is switched to "H" level.

## (5) E/W Enable

Executing E/W Enable instruction sets E/W enable mode and enables Program and Chip Erase instructions.

## (6) E/W Disable

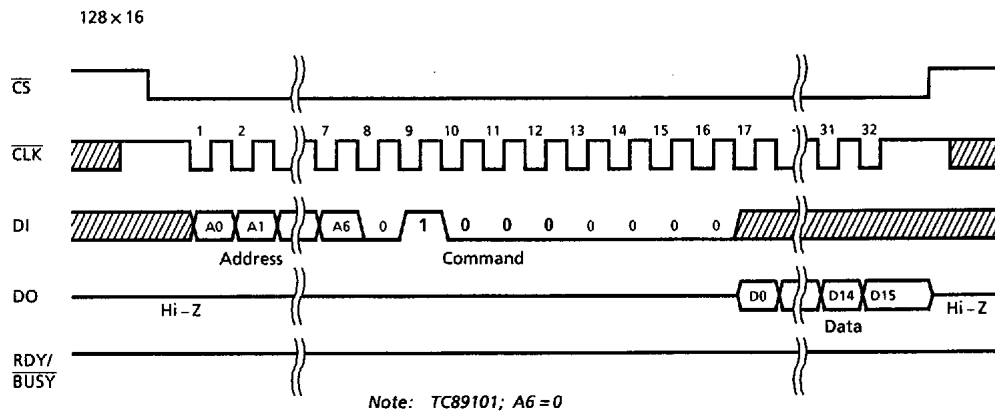
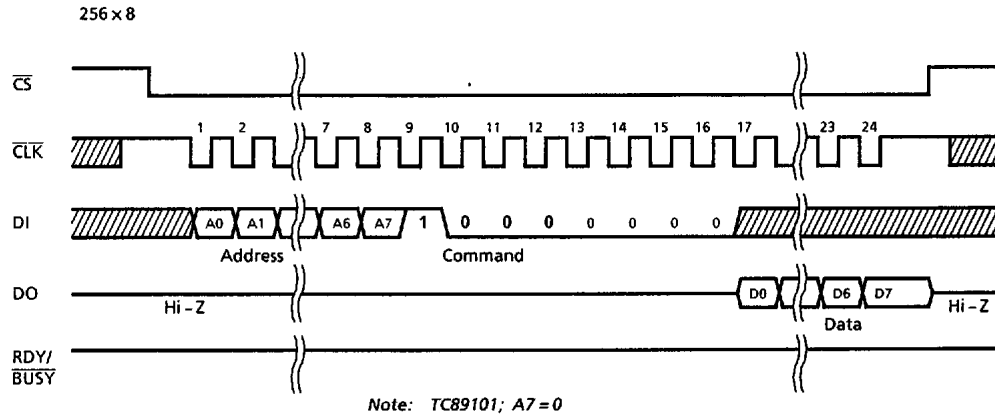
Executing E/W Disable instruction sets the E/W disable mode and disables both the Program and Chip Erase instructions. Once E/W disable mode is set, E/W disable mode is held until E/W Enable instruction is executed.

## 3. CAUTIONS WHEN TURNING THE POWER ON AND OFF

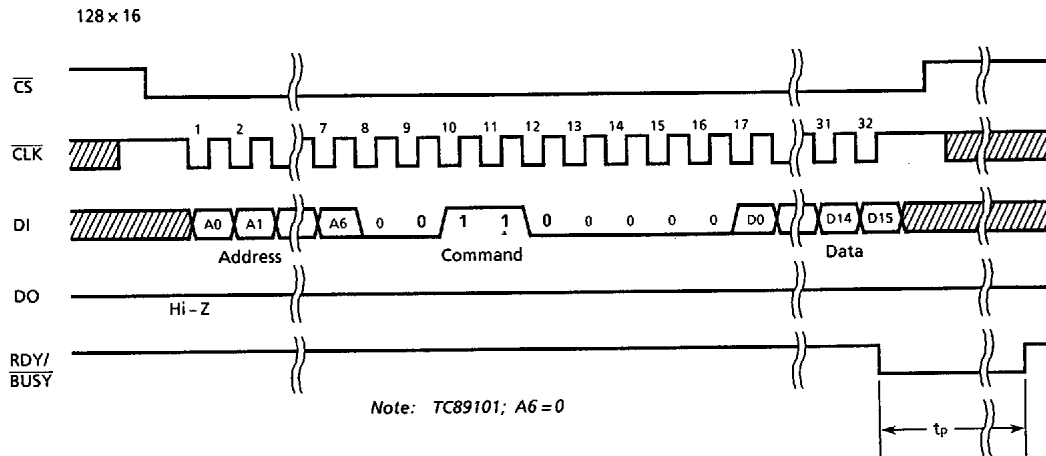
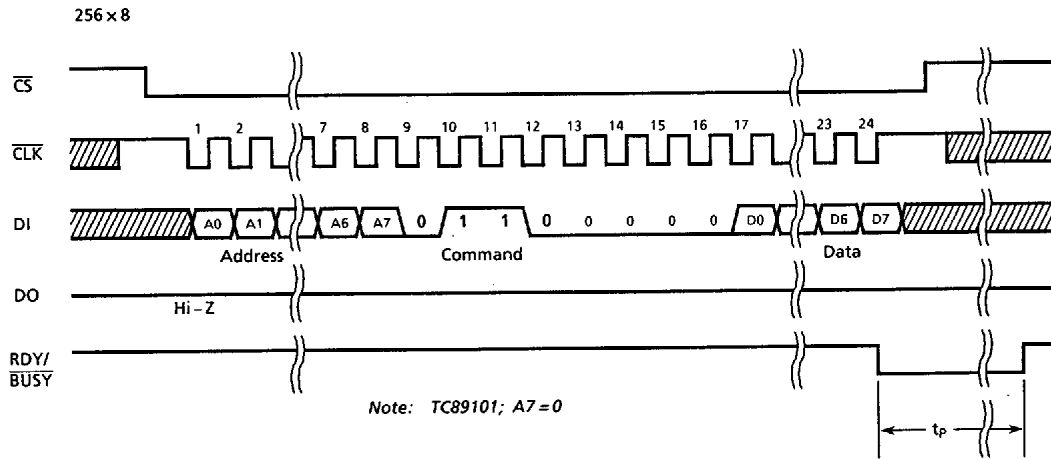
- (1) After turning the power on, wait 1ms for warm-up before executing instruction.
- (2) After turning the power on, set either the E/W enable mode or E/W disable mode.
- (3) If the power supply voltage is lower the approximately 3.5V, E/W Disable instruction is automatically executed internally.

4. TIMING DIAGRAMS

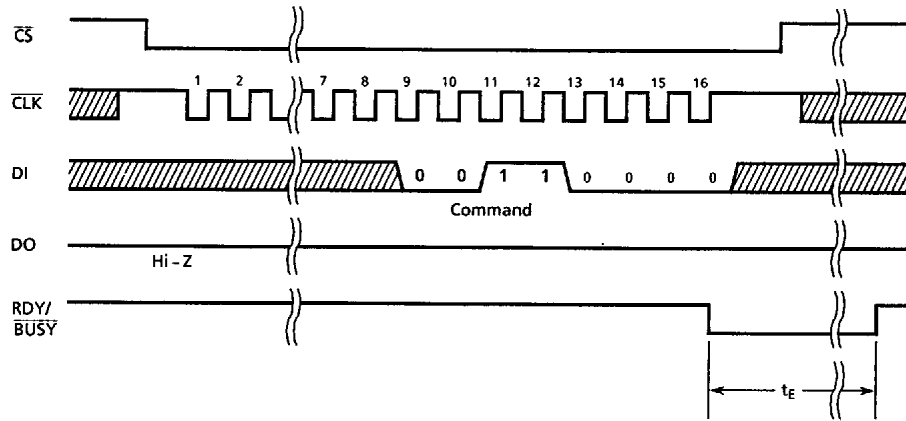
(1) Read



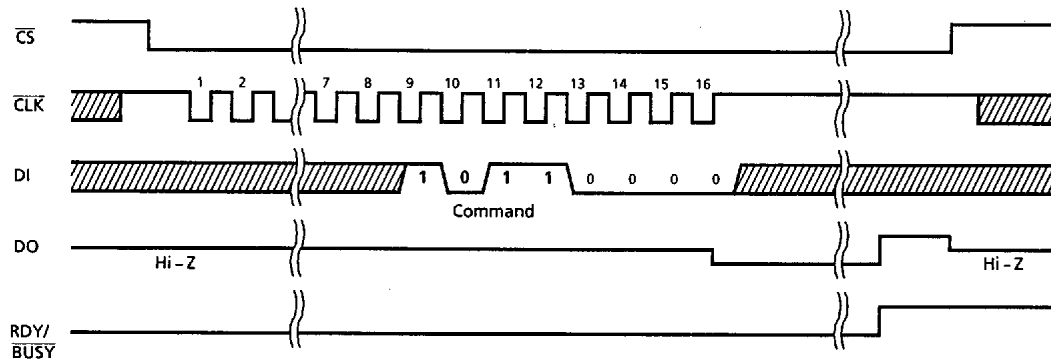
(2) Program



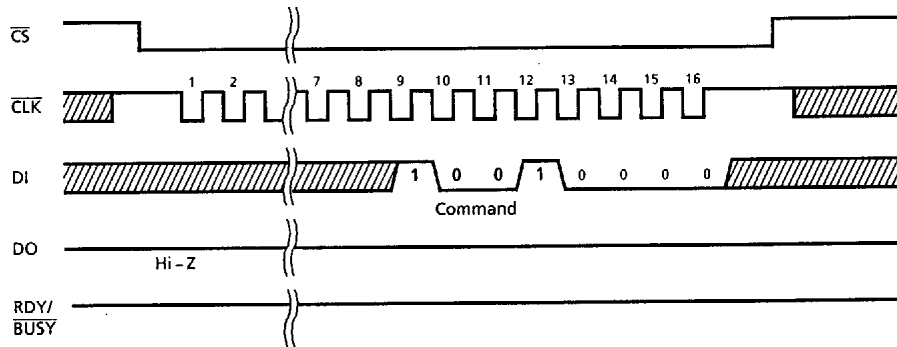
(3) Chip Erase



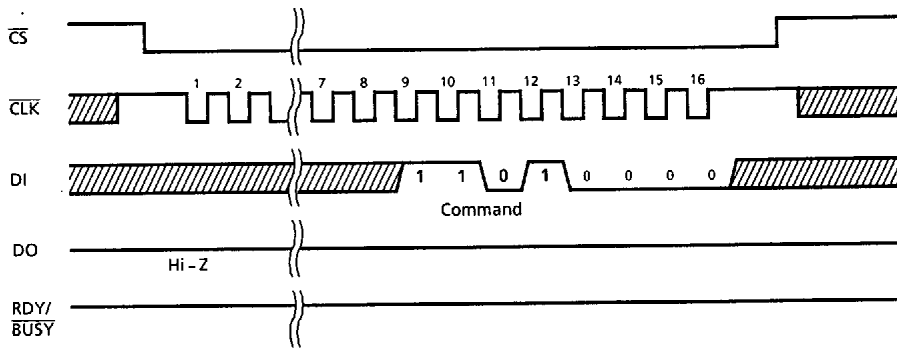
(4) Busy Monitor



(5) E/W Enable



(6) E/W Disable



## ELECTRICAL CHARACTERISTICS

## ABSOLUTE MAXIMUM RATINGS (GND = 0V)

PARAMETER	SYMBOL	RATINGS	UNITS
Supply Voltage	$V_{CC}$	- 0.3 to 7	V
Input Voltage	$V_{IN}$	- 0.3 to $V_{CC} + 0.3$	V
Output Voltage	$V_{OUT}$	- 0.3 to $V_{CC} + 0.3$	V
Power Dissipation	PD	600	mW
Soldering Temperature (time)	$T_{sld}$	260 (10sec)	°C
Storage Temperature	$T_{stg}$	- 55 to 125	°C
Operating Temperature	$T_{opr}$	0 to 70	°C

RECOMMENDED OPERATING CONDITIONS (GND = 0V,  $T_{opr} = 0$  to 70°C)

PARAMETER	SYMBOL	PINS	CONDITIONS	Min.	Max.	UNITS
Supply Voltage	$V_{CC}$			4.5	5.5	V
Input Low Voltage	$V_{IL}$		$V_{CC} = 4.5V$	0	0.8	V
Input High Voltage	$V_{IH1}$	$\overline{CS}$ , DI, ORG	$V_{CC} = 5.5V$	2.0	$V_{CC}$	V
	$V_{IH2}$	$\overline{CLK}$		3.0		
Clock Frequency	$f_{CLK}$			0	1	MHz

D.C. CHARACTERISTICS (GND = 0V,  $T_{opr} = 0$  to 70°C)

PARAMETER	SYMBOL	CONDITIONS	Min.	Typ.	Max.	UNITS
Input Current	$I_{LI}$		-	-	$\pm 10$	$\mu A$
Output Leakage Current	$I_{LO}$		-	-	$\pm 10$	$\mu A$
Output High Voltage	$V_{OH}$	$V_{CC} = 4.5V$ , $I_{OH} = -400\mu A$	2.4	-	-	V
Output Low Voltage	$V_{OL}$	$V_{CC} = 4.5V$ , $I_{OL} = 2.1mA$	-	-	0.4	V
Supply Current	$I_{CC0}$		-	-	2	mA
	$I_{CCP}$	During Program or Chip Erase	-	-	10	mA
	$I_{CCS}$	$\overline{CS} = 1$ (Except Program or Chip Erase operation)	-	-	100	$\mu A$

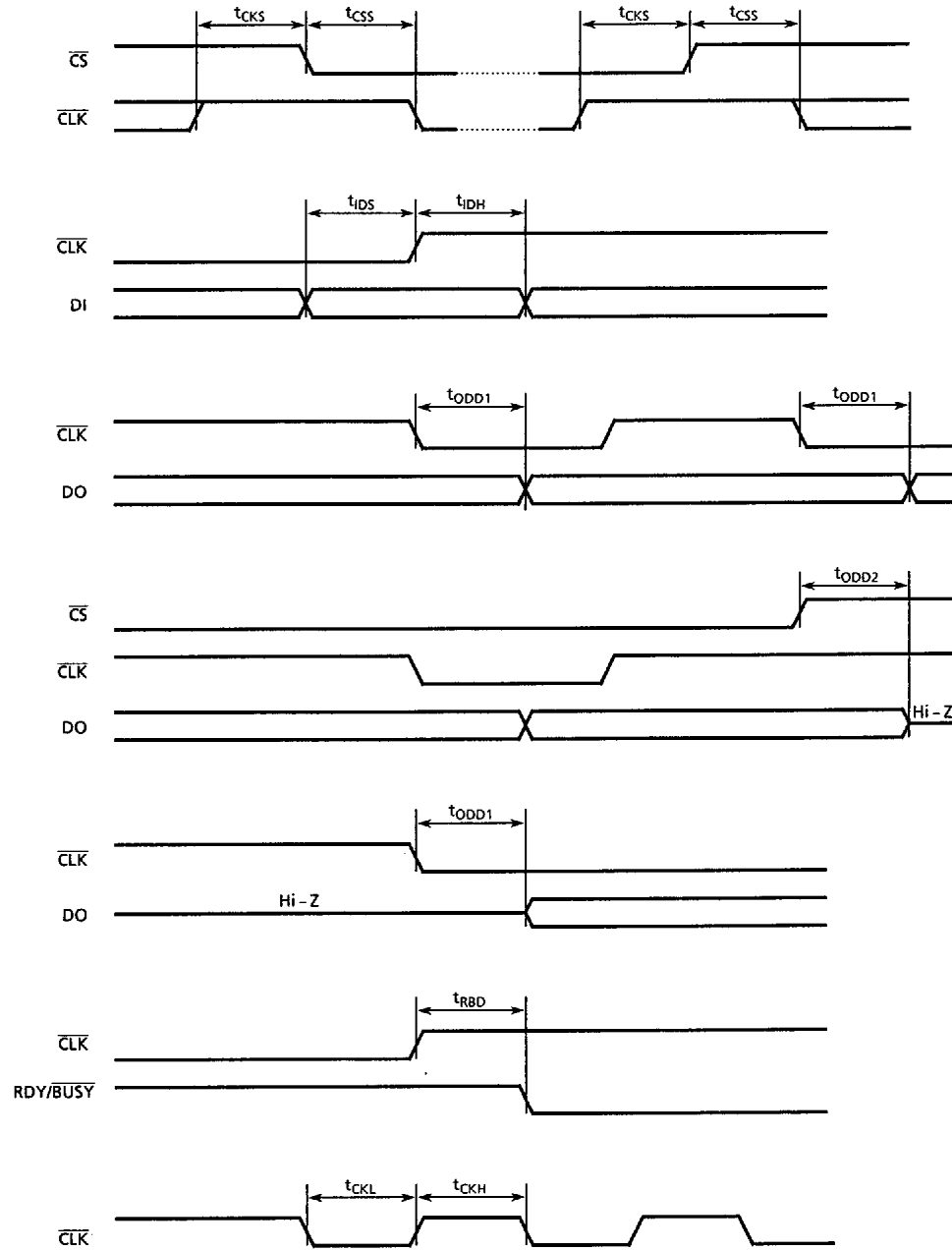


A.C. CHARACTERISTICS	(GND = 0V, V <sub>CC</sub> = 4.5 to 5.5V, T <sub>opr</sub> = 0 to 70°C)
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PARAMETER	SYMBOL	Min.	Max.	UNITS
CLK Frequency	f <sub>CLK</sub>	0	1	MHz
CLK Low Time	t <sub>CKL</sub>	400	-	ns
CLK High Time	t <sub>CKH</sub>	400	-	ns
CLK Input Setup Time	t <sub>CKS</sub>	250	-	ns
$\overline{CS}$ Input Setup Time	t <sub>CS</sub>	250	-	ns
DO Output Delay Time (Note)	t <sub>ODD1</sub>	-	250	ns
	t <sub>ODD2</sub>	-	500	ns
RDY/BUSY Output Delay Time	t <sub>RBD</sub>	-	250	ns
DI Input Setup Time	t <sub>DS</sub>	250	-	ns
DI Input Hold Time	t <sub>DH</sub>	250	-	ns
Chip Erase Time	t <sub>E</sub>	-	20	ms
Program Time	t <sub>P</sub>	-	20	ms
Erase/Write Cycle	N <sub>EW</sub>	10 <sup>4</sup>	-	cycles
Data Retention Time	t <sub>RET</sub>	10	-	years

Note: C<sub>L</sub> = 100pF, V<sub>OH</sub>/V<sub>OL</sub> = 2.0V/0.8V

A.C. CHARACTERISTICS TIMING DIAGRAMS



INPUT / OUTPUT CIRCUITRY

PIN NAME	I/O	CIRCUITRY	REMARKS
$\overline{CS}$ DI ORG	Input		
$\overline{CLK}$	Input		Hysteresis input
DO	Output		Initial "Hi-Z"
$\overline{RDY}/\overline{BUSY}$	Output		Initial "High"